

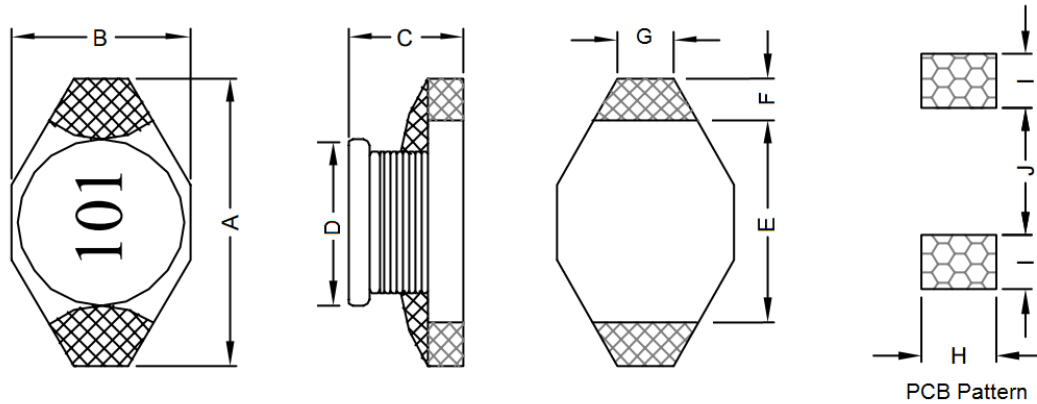
1. Part No. Expression

PDB16081R0MZF

(a) (b) (c) (d)(e)(f)

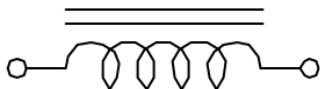
- (a) Series Code
- (b) Dimension Code
- (c) Inductance Code
- (d) Tolerance Code
- (e) Special Code
- (f) Packaging Code

2. Configuration & Dimensions: (Unit:- mm)



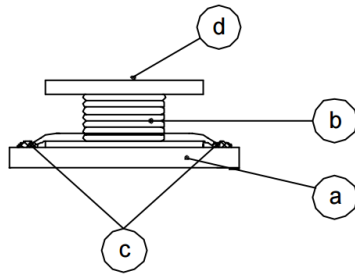
A	B	C	D	E	F	G	H	I	J
6.60 Max	4.45 Max	2.92 Max	3.90 Ref	4.32 Ref	1.02 Ref	1.27 Ref	3.56 Ref	1.40 Ref	4.06 Ref

3. Schematic



NOTE: Specifications subject to change without notice. Please check our website for latest information.

4. Material List



- (a) Base
- (b) Wire
- (c) Epoxy
- (d) Marking

5. General Specifications

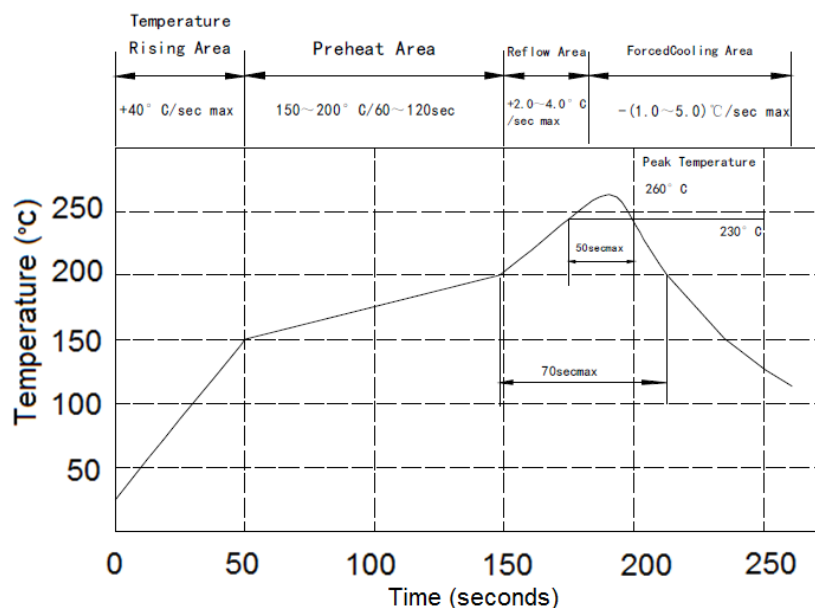
- (a) Operating Temperature: -40°C to $+125^{\circ}\text{C}$ (Including self - temperature rise).
- (b) Storage Temperature: -40°C to $+125^{\circ}\text{C}$ (On board).
- (c) Irms: Base on temperature rise $\Delta T = 40^{\circ}\text{C}$ Max.
- (d) Isat: Base on inductance change $\Delta L/L_0 = 10\%$ Typ.
- (e) Storage Condition (Component in its packaging)
 - i) Temperature: Less than 40°C .
 - ii) Humidity: 70% RH.

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6. Electrical Characteristics

Part Number	Inductance (uH)	Test Frequency (Hz)	SRF (MHz) Typ.	DCR (Ω) Max.	I _{rms} (A)	I _{sat} (A)
PDB16081R0MZF	1.0±20%	0.1V/100K	130.0	0.05	2.90	2.90
PDB16081R5MZF	1.5±20%	0.1V/100K	115.0	0.06	2.80	2.60
PDB16082R2MZF	2.2±20%	0.1V/100K	90.0	0.07	2.40	2.30
PDB16083R3MZF	3.3±20%	0.1V/100K	70.0	0.08	2.00	2.00
PDB16084R7MZF	4.7±20%	0.1V/100K	50.0	0.09	1.50	1.50
PDB1608100MZF	10.0±20%	0.1V/100K	35.0	0.16	1.10	1.10
PDB1608150MZF	15.0±20%	0.1V/100K	30.0	0.23	1.00	0.90
PDB1608220MZF	22.0±20%	0.1V/100K	20.0	0.37	0.80	0.70
PDB1608330MZF	33.0±20%	0.1V/100K	15.0	0.51	0.60	0.58
PDB1608470MZF	47.0±20%	0.1V/100K	14.0	0.64	0.50	0.50
PDB1608680MZF	68.0±20%	0.1V/100K	11.0	0.86	0.40	0.40
PDB1608101MZF	100.0±20%	0.1V/100K	9.0	1.27	0.30	0.31

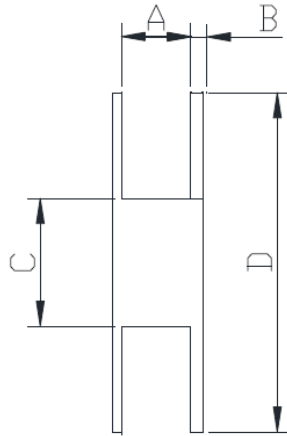
7. Soldering Profile



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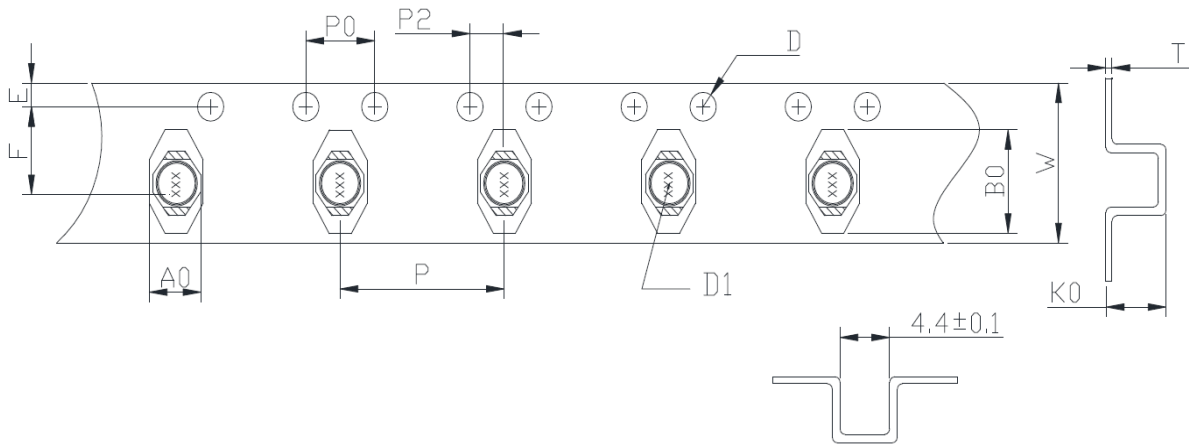
8. Packaging Information

8-1 Reel Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
13"x16mm	16.5	2.3	100.0	330.0

8-2 Tape Dimension



W(mm)	E(mm)	F(mm)	P(mm)	P0(mm)	P2(mm)	D0(mm)	D1(mm)	T(mm)	A0(mm)	B0(mm)	K0(mm)
16.0±0.3	1.75±0.10	7.5±0.1	8.0±0.1	4.0±0.1	2.0±0.1	1.5±0.1	1.5±0.25	0.35±0.05	4.5±0.1	6.8±0.1	3.2±0.1

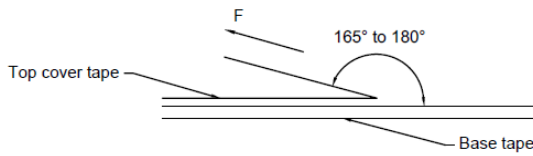
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8-3 Packaging Quantity

Chip Size	PDB1608
Chip/Reel	2,500
Inner Box	7,500
Outer Box	15,000

8-4 Tearing Off Force



The force for tearing off cover tape is 5 to 120 grams in the arrow direction under the following conditions.

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

Application Notice:

1. Storage Conditions:

To maintain the solderability of terminal electrodes:

- a) Recommended products should be used within 12 months from the time of delivery.
- b) The packaging material should be kept where no chlorine or sulfur exists in the air.

2. Transportation:

- a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- b) Vacuum pick up is strongly recommended for individual components.
- c) Bulk handling should ensure that abrasion and mechanical shock are minimized.

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